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Amendments to the Claims

1. (Currently Amended) A commercially mass-produced, for good profit, integrated circuit (IC) containing therein having multiple active circuit components each having a feature size accurate to better than a few hundred atomic layers, comprising:

a solid substrate of one conductivity type;

a solid material pocket of a different conductivity type having a side surface and positioned on a selected top surface of said substrate;

a signal-translating, electronic rectifying barrier located between said solid material pocket and the selected top surface of said substrate; and

a solid state material region adjoining said solid substrate, said electronic rectifying barrier, and the side surface of said solid material pocket and, together with said electronic rectifying barrier, electrically isolating a selected active circuit component from another neighboring active circuit component to make these two active circuit components electrically independently operable;

said solid state material region having a depth accuracy of better than 0.13 microns and being continuously and perfectly bonded metallurgically to all said solid substrate, said solid material pocket, and said electronic rectifying barrier, without thermally and electrically insulating voids and microcracks visible at 1,000 times magnification in interfacial bonding regions between the bonded device components;

said solid state material region at a lower portion thereof having a curved bottom of zero width for maximum device miniaturization necessary for modern microelectronics;

said curved bottom contacting said electronic rectifying barrier and having a differentially expanded peripheral surface to minimize voltage gradient and leakage current thereby ensuring high device yield, low cost, and good performance; and

the lower curved bottom of said solid state material region having a radius of curvature of less than 0.1 microns and located at a depth of less than  $h = 0.3$  microns to have an equivalent level angle of less than 0.810 radians.

2. (Canceled)

3. (Currently Amended) A mass-produced integrated circuit as in claim 1 in which a lateral edge of at least one of said solid substrate, said solid material pocket, and said electronic rectifying barrier has a specified lateral dimension, ~~said specified dimension having an accuracy of accurate~~ to better than a few hundred atomic layers.

4. (Canceled)

5. (Previously Presented) A mass-produced integrated circuit as in claim 1 in which a selected significant portion of a major surface of at least one of said solid material pocket, said selected top surface of said substrate, said solid state material region, and said electronic rectifying barrier gradually changes a vertical thickness thereof with closeness in a lateral direction to a lateral edge of said electronic rectifying barrier.

6. (Previously Presented) A mass-produced integrated circuit as in claim 1 in which a selected significant portion of at least one of said solid material pocket, said selected top surface of said solid substrate, said solid state material region, and said electronic rectifying barrier monotonically changes a vertical thickness thereof with closeness in a lateral direction to a lateral edge of said electronic rectifying barrier.

7. (Canceled)

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15. (Currently Amended) A mass-produced integrated circuit as in claim 1 in which at least one of the top and bottom major surfaces of said electronic rectifying barrier is curved.

16. (Previously Presented) A mass-produced integrated circuit as in claim 1 in which a selected portion of said electronic rectifying barrier has a vertical thickness which gradually increases with closeness in a lateral direction to a lateral edge of said electronic rectifying barrier.

17. (Canceled)

18. (Previously Presented) A mass-produced integrated circuit as in claim 1 in which said electronic rectifying barrier is thin and has

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a lateral-extending dimension of less than one micron.

19. (Currently Amended) A mass-produced integrated circuit as in claim 1 in which:

said solid state material region consists essentially of a solid material selected from the group consisting of oxide, glass, organics, semiconductor, non-semiconductor, intrinsic semiconductor, a solid comprising metal, intermetallics, dielectric material, and an electrically insulating solid;

said electronic rectifying barrier is selected from the group consisting of a PN junction, a heterojunction, a metal-oxide junction, and a Schottky barrier; and

said solid material pocket is of a semiconductor material selected from the group consisting of Ge, Si, GaAs, GaP, InP, InSb, other III-V semiconductor compounds, other II-VI semiconductor compounds, and a mixture thereof.

20. (Currently Amended) A commercially mass-produced, miniaturized integrated-circuit semiconductor device containing therein multiple transistors wherein each having a feature size accurate to better than a few hundred atomic layers, comprising:

a first semiconductor material body having a first polarity;

a second semiconductor material body located generally vertically underneath said first semiconductor material body and having a second polarity that is opposite the first polarity;

a signal-translating, electronic rectifying barrier formed between said first and second semiconductor material bodies; and

a third solid state material body having an electrical conductivity at least one order orders of magnitude different from those of said first and second semiconductor material bodies and directly contacting respective portions of each of said first and second semiconductor material bodies and said electronic rectifying barrier and, together with said electronic rectifying barrier,

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electrically isolating a selected transistor in said semiconductor device from another neighboring transistor in the same semiconductor device thereby making these two transistors electrically independently operable;

said third solid state material body having two differentially surface-expanded sides that are not parallel to each other to thereby form on said third solid state material body a curved bottom terminal portion of zero width for maximum device miniaturization necessary for modern microelectronics ~~no more than a micron in thickness in a selected direction; said thickness having an accuracy of better than a few hundred atomic layers;~~

said curved bottom terminal portion contacting said electronic rectifying barrier and having a differentially expanded peripheral surface to minimize voltage gradient and leakage current thereby ensuring high device yield, low IC cost, and good device performance.

21. (Canceled)

22. (Previously Presented) A semiconductor device as in claim 20 in which at least one of said first semiconductor material body, said second semiconductor material body, and said third solid state material body is of an intrinsic semiconductor material.

23. (Previously Presented) A semiconductor device as in claim 20 in which said third solid state material body has an as-formed metallurgically graded-seal type with respect to at least one of said first and second semiconductor material bodies.

24. (Currently Amended) A semiconductor device as in claim 20 in which the bottom terminal portion of said third solid state material body is vertically within less than a distance from a selected point inside said electronic rectifying barrier;

said distance being selected from the group consisting of one

micron and 0.1 microns.

25. (Previously Presented) A semiconductor device as in claim 20 in which said third solid state material body has a geometry, position, and orientation relative to said first and second semiconductor material bodies, to allow adequate stress and strain modification on said electronic rectifying barrier thereby improving device performance.

26. (Previously Presented) A semiconductor device as in claim 25 in which said third solid state material body is favorably stressed, and has a blunt and rounded bottom of zero width so that lateral mismatch stresses at the bottom in the zero width direction is also zero, and

in which the rounded bottom of said third solid state material body is located within a specified distance from a designated point inside said electronic rectifying barrier to achieve a beneficial proximity effect;

said specified distance being selected from the group consisting of one micron and 0.1 microns.

27. (Canceled)

28. (Previously Presented) A semiconductor device as in claim 20 in which said third solid state material body is of an electrically insulating material selected from the group consisting of an oxide, a nitride, organics, semiconductor, a solid comprising metal, intermetallics, a dielectric material, intrinsic semiconductor, other insulator, or a mixture thereof.

29. (Canceled)

30. (Previously Presented) A semiconductor device as in claim 20

in which said third solid state material body has a designed, three-dimensionally controlled shape, size, vertical dimension and location accurate to fractional microns.

31. (Previously Presented) A semiconductor device as in claim 20 in which said third solid state material body has a rounded bottom portion forming an inverted arch making the device more mechanically stable and reliable.

32. (Previously Presented) A semiconductor device as in claim 20 in which the terminal portion of said third solid state material body is less than 1 micron wide in a selected direction.

33. (Previously Presented) A semiconductor device as in claim 20 in which said electronic rectifying barrier has a curved major surface.

34. (Previously Presented) A semiconductor device as in claim 20 in which said third solid state material body has a cylindrical surface.

35. (Canceled)

36. (Previously Presented) A semiconductor device as in claim 20 in which said electronic rectifying barrier is stressed to improve a performance of said semiconductor device.

37. (Canceled)

38. (Currently Amended) A semiconductor device as in claim 20 in which:

said third solid state material body consists essentially of a material selected from the group consisting of a solid, an

electrically insulating solid, oxide, glass, organics, semiconductor, non-semiconductor, a solid comprising metal, intermetallics, a ~~dielectical~~ dielectrical material, intrinsic semiconductor, and a mixture thereof;

said electronic rectifying barrier is selected from the group consisting of a PN junction, PI junction, NI junction, metal-oxide, oxide-semiconductor, interfacial rectifying barrier, heterojunction, other optoelectromagnetically active signal-translating region, a Schottky barrier; and a mixture thereof;

said first semiconductor material body is of a semiconductor material selected from the group consisting of Ge, Si, GaAs, GaP, InP, InSb, other III-V semiconductor compounds, other II-VI semiconductor compounds, and a mixture thereof.

39. (Canceled)

40. (Canceled)

41. (Canceled)

42. (Canceled)

43. (Canceled)

44. (Canceled)

45. (Previously Presented) An ~~integrated circuit~~ as in claim 1, in which said electronic rectifying barrier adjoins both said solid substrate and said solid state material region at a place where a periphery of said electronic rectifying barrier is differentially surface-expanded vertically to passivity the adjoining rectifying barrier and to reduce noise, instability, leakage current, electrical shorts, and failure due to low breakdown voltage.

46. (Previously Presented) An integrated circuit as in claim 1 in which said solid state material region is a vertically elongated region of less than 1 micron in width or size with an accuracy of less than 0.13 microns, and having a bottom of a shape selected from the group consisting of flat, rounded, cylindrical, hemispherical, and conical or V-shaped.

47. (Currently Amended) An integrated circuit as in claim 1 including means for circulating a rapidly moving cooling fluid in a microscopic vicinity of said signal--translating, electronic rectifying barrier to achieve surface cooling of said electronic rectifying barrier.

48. (Previously Presented) An integrated circuit as in claim 1 in which said electronic rectifying barrier has a lateral edge, and at least one of said solid material pocket, said electronic rectifying barrier, and said solid state material region has a portion thereof which gradually and continuously changes its vertical thickness with closeness to a lateral edge of said electronic rectifying barrier.

49. (Currently Amended) An integrated circuit as in claim 1 in which at least one of said solid material pocket, said rectifying barrier, and said solid state material region has a selected- portion thereof which gradually and monotonically changes its vertical thickness with closeness to a lateral edge of said electronic rectifying barrier.

50. (Currently Amended) An Integrated circuit as in claim 1 in which a selected portion of at least one of a major surface of said solid material pocket, said electronic rectifying barrier, and said solid state material region is curved.

51. (Canceled)

52. (Currently Amended) An integrated circuit as in claim 1 in which said solid state material region is an elongated deep, and narrow, ~~solid state material region~~; and including:

a second elongated, deep and narrow, solid state material region microscopically close to said elongated deep and narrow, solid state material region;

each of said two elongated, deep and narrow, solid state material regions being within a micron of both said solid substrate and said electronic rectifying barrier;

said second elongated, solid state material region having a submicron width or size at a terminal portion thereof where it is closest to said electronic rectifying barrier; and

both said two elongated, solid state material regions having ~~aspect ratios exceeding 3~~, being oriented normally of a common major bottom surface of said solid substrate, and extending downward from a common top major surface of said solid material pocket whereby said two elongated, solid state material regions are parallel to each other.

53. (Presently Presented) An integrated circuit as in claim 52 in which said two elongated, solid state material regions have different lengths so that these two solid state material regions reach different depths inside said solid substrate.

54. (Previously Presented) An integrated circuit as in claim 52 in which said two elongated, solid state material regions differ in electrical conductivity by at least one order of magnitude from that of the material of said semiconductor material pocket.

55. (Canceled)



56. (Currently Amended) An integrated circuit as in claim 52 ± in which:

materials of said solid material pockets and said solid state material regions are solids which are 100% dense, substantially chemically pure and uniform, and non-contaminating, and impervious to contaminating gases;

at least one of said two solid state material regions is stressed to favorably affect a device performance, and has a rounded bottom of zero width so that lateral mismatch stresses at the bottom in the zero width direction is also zero,

said electronic rectifying barrier is located within a specified distance, with a fractional micron accuracy, from a designated point inside said electronic rectifying barrier to achieve a beneficial proximity effect; and

said specified distance being selected from the group consisting of one micron and 0.1 microns.

57. (Currently Amended) A commercially mass-produced, low-cost miniaturized solid state, integrated circuit device containing therein multiple transistors each having a feature size accurate to better than a few hundred atomic layers, comprising

a first solid state material of a first conductivity type;

a second solid state material of a second conductivity type and positioned under the first solid state material, the first and second solid state materials having respective adjoining portions;

a signal-translating, ~~rectifying~~ barrier region lying between and directly contacting the respective adjoining portions; and

a device material region starting at least in the first solid state material and extending toward the rectifying barrier region to form a lower bottom which is within a micron below a selected point inside the rectifying barrier region to thereby combine with said rectifying barrier region for electrically isolating a selected

transistor from another neighboring transistor;

a major portion of a top surface area of device chip being occupied by said multiple transistors themselves and not by inert or inactive device material regions thereby achieving radically improved, device miniaturization;

said device material region having ~~at a lower portion thereof a curved~~ a rounded bottom of zero width for maximum device miniaturization necessary for modern microelectronics;

said ~~curved~~ rounded bottom contacting the electronic rectifying barrier and having a differentially expanded peripheral surface to minimize voltage gradient and leakage current thereby ensuring high device yield, low IC cost, and good device performance.

58. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the rectifying barrier region is selected from the group consisting of PN junction, metal-semiconductor or Schottky barriers, heterojunction, metal-oxide, other electrically rectifying barriers, and a mixture thereof;

at least one of the first and second solid state materials is selected from the group consisting of Si, Ge, GaAs, GaP, InP, InSb, intrinsic semiconductor, III-V semiconducting compound, II-VI semiconducting compound, and a mixture thereof;

the device material region penetrates downward through the rectifying barrier region to reach the second solid state material and, in combination with the rectifying barrier region, electrically isolates said multiple transistors from one another + and

a bottom of the device material region is less than 0.1 microns and close to zero microns below the rectifying barrier region.

59. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the device material region has a bottom which is closer to zero microns than 0.1 microns below the rectifying barrier region.

60. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the device material region is an elongated device material region; is accurate to less than a micron in a dimension selected from the group consisting of shape, size, depth, and chemical composition profiling, and consists essentially of a device material selected from the group consisting essentially of air, gas, oxide, nitride, glass, organics, semiconductor, non-semiconductor, a solid comprising metal, intermetallics, dialectical material, other electrically insulating material, and a mixture thereof.

61. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 60 in which a bottom of the elongated device material region is close to zero microns below the rectifying barrier region.

62. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 60 in which the elongated, device material region has an intentionally designed and produced rounded bottom having a vertically curved peripheral surface thereat;

the rectifying barrier region adjoining the rounded bottom of the elongated device material region and having a matching curved peripheral surface thereon thereby passivating and differentially expanding greatly the curved peripheral surface of the rectifying barrier region for protection against Type I contaminants, for eliminating wasteful central flat portions at bottoms of similar device material regions in prior art devices, for reducing mismatch thermal stresses leading to electrical device failures, for minimizing electrical field gradient across a surface-passivated and expanded, rectifying barrier region, and for improving mechanical and electrical device yields and reliabilities.

63. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which only a minor portion of a top surface area of device chip is not occupied by said multiple transistors themselves;

said multiple transistors having no centrally large and flat oxidized isolation ~~grooves~~ bottoms, ~~as in of Deltzer and Murphy devices~~ thereby achieving radically improved device miniaturization.

64. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the first solid state material is purposely broken up into a plurality of smaller material patches so that mismatch stresses from varying coefficients of material thermal expansions are reduced in proportion to the smaller size of the broken material patches thereby improving device performance.

65. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the device material region is an elongated, cylindrical device material groove having a rounded groove bottom ~~and an aspect ratio of over 3 to 5~~, and a cylindrical radius of less than one micron, and is oriented generally normally of a top major surface of the second solid state material.

66. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 65 in which the elongated, cylindrical device material is a groove which is purposely tilted relative to a top surface of the second solid state material so that the device material groove is above a bottom plane of the rectifying barrier region at some places where the groove depth is less than zero (or  $h < 0$ ), substantially coincides with the same bottom plane of the rectifying barrier region at another place where the groove depth is zero (i.e.,  $h = 0$ ), but lies below the same bottom plane of the rectifying barrier region at other places where the growth depth is greater than zero (or  $h > 0$ ).

67. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 65 in which the elongated, cylindrical device material groove has a cylindrical radius of less than one micron.

68. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 65 including at least one additional, elongated, cylindrical device material groove oriented normally of a top major surface of the second solid state material, and microscopically close to the other elongated, cylindrical device material groove;

both the two device material grooves having sizes of less than two microns and different lengths to thereby extend vertically downward from a common higher, vertical level to different depths into the second solid state material.

69. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 65 in which a bottom of the elongated cylindrical device material groove has a groove depth of less than 0.1 microns but microscopically close to zero microns and designed specifically for at least one of thermal, magnetic, and electrical contacting or for optical communication to the device, without actual physical exposure to ambient of the second solid state material.

70. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 65 in which the elongated, cylindrical device material groove ~~is real-time feedback controlled to~~ has a submicron accuracy in a depth to as close to zero microns below the rectifying barrier region as possible, yet still to have a meaningful device yield to be commercially viable because of the submicron depth accuracy.

71. (Currently Amended) A mass-produced, solid state integrated

circuit device as in claim 65 in which the elongated, cylindrical device material groove has said rounded bottom; and

the rectifying barrier region adjoins said rounded bottom of the device material groove at a curved peripheral surface thereof, thereby vertically maximizing the peripheral surface expansion and minimizing electrical field gradient across the rectifying barrier region to improve device yield and manufacturability.

72. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the device material region is an elongated groove having a microscopically precise groove bottom surface suitable for introducing a precise amount and shape of a foreign matter therethrough ~~through the highly precise groove bottom surface~~, thereby achieving microscopically precise three-dimensional control as to shape, size, and position of a region of the foreign matter introduction into the device.

73. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the device material region is a vertical and ~~electrically insulating~~, elongated device material groove; and

a lower end of the vertical, elongated groove has a centrally rounded bottom of substantially zero width in a direction parallel to a top major surface of the second solid state material whereby mismatch stresses arising from varying coefficients of thermal expansions of different materials in the device are substantially zero in the direction thereby improving device yield, performance, and reliability;

a first selected point on the centrally rounded bottom of said first device material region having a first non-zero radius of curvature while a second selected point on the centrally rounded bottom of said second device material region having a second non-zero radius of curvature;

said ~~sad~~ first and second non-zero radii of curvature differing from each other in a way selected from the group consisting of: a) significantly; b) differing by over several times; 3) differing by over one order of magnitude; and 4) differing by over two orders of magnitude; and

said first and second selected points being both vertically and laterally within one micron of each other.

74. (Currently Amended) A mass-produced, solid state integrated circuit device as in claim 57 in which the rectifying barrier region has a curved peripheral surface to achieve enhanced device reliability; increase yield; decreased cost; improved junction surface passivation; increased packing density; increased switching speed; reduced noise, instability, leakage current and electrical shorts; improved breakdown voltage; controlled carriers generation, movement, and recombination at or near the junction region peripheral surface; and regulated optoelectromagnetic interaction of the rectifying barrier region with ambient or contacting material.

75. (Canceled)

76. (Previously Presented) A commercially mass-produced IC of Claim 1, in which a selected surface of one of said solid substrate, said solid material pocket, and said rectifying barrier contacts a non-flat surface on a number of the rest of said solid substrate, said solid material pocket, and said rectifying barrier; said number being one or two.

77. (Previously Presented) A commercially mass-produced IC of claim 76 in which:

said selected surface is selected from the group consisting of a side surface, a top major surface, and a bottom major surface; and has ~~having~~ a shape selected from the group consisting of: (a) a

round surface; (b) a major-portion rounded surface; and (3) a surface rounded in its entirety.

78. (Currently Amended) A commercially mass-produced IC of claim 1 in which, on a vertical cross-section thereof, two selected points

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